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Product Change Notification - JAON-17PTTA126

Date: 20 Jun 2016
Product Category: Supertex
Notification subject: CCB 1720 Final Notice: Qualification of ASEW assembly site for CL2, CL6, LR8 and CL220 device families available in 3L DPAK package using 84-1LMISR4 die attach and CEL-9240HF10AK molding compound.
Notification text: **PCN Status:** Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASEW assembly site for CL2, CL6, LR8 and CL220 device families available in 3L DPAK package using 84-1LMISR4 die attach material and CEL-9240HF10AK molding compound.

Pre Change:

Assembled at GEMC using EME G600 molding compound.

Post Change:

Assembled at GEMC using EME G600 molding compound or assembled ASEW using CEL-9240HF10AK molding compound.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	GEMC assembly site	GEMC assembly site	ASEW assembly site
Wire material	Au wire	Au wire	Au wire
Die attach material	84-1LMISR4	84-1LMISR4	84-1LMISR4
Molding compound material	EME-G600	EME-G600	CEL-9240HF10AK
Lead frame material	PMC90	PMC90	PMC90

Impacts to Data Sheet:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASEW as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 15, 2016 (date code: 1628)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	August 2015				---->	June 2016					July 2016			
	32	33	34	35		22	23	24	25	26	27	28	29	30
Initial PCN Issue Date				X										
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date												X		

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

August 26, 2015: Issued initial notification.

June 20, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from December 15, 2015 to July 15, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-17PTTA126_Qual_Report.pdf](#)
- [PCN_JAON-17PTTA126_Affected_CPn.pdf](#)
- [PCN_JAON-17PTTA126_Affected_CPn.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-17PTTA126
CATALOG_PART_NBR
CL2K4-G
CL6K4-G
LR8K4-G
CL220K4-G